| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L4 | 2 | jp-2001284382-$.did. | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/01/27 17:14 |
| L5 | 20245 | solder near2 (ball$8 bump$6) | US-PGPUB; USPAT | OR | ON | 2005/01/27 17:16 |
| L6 | 31 | L5 with flux$6 with solid | US-PGPUB; USPAT | OR | ON | 2005/01/27 17:16 |
| S1 | 2 | "20030164552".pn. "20030189249".pn. | US-PGPUB; USPAT | OR | OFF | 2005/01/27 08:11 |
| S2 | 2 | "20030164552".pn. "20030189249".pn. | US-PGPUB; USPAT | OR | OFF | 2005/01/27 08:12 |
| S3 | 14303 | solder near2 (ball$8 bump$6) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/27 08:30 |
| S4 | 961 | S3 same flux$6 | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/27 08:30 |
| S5 | 185 | S4 and (wafer semiconductor chip die dice) and ((active adj surface) pad underbump (under adj bump)) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/27 09:09 |
| S6 | 20245 | solder near2 (ball$8 bump$6) | US-PGPUB; USPAT | OR | ON | 2005/01/27 08:38 |
| S7 | 1801 | S6 with flux$6 | US-PGPUB; USPAT | OR | ON | 2005/01/27 17:15 |
| S8 | 516 | S7 and ((wafer semiconductor chip die dice) same ((active adj surface) (bond adj pad) underbump (under adj bump))) | US-PGPUB; USPAT | OR | ON | 2005/01/27 08:41 |
| S9 | 1321 | S7 and ((wafer semiconductor chip die dice) same ((active adj surface) pad underbump (under adj bump))) | US-PGPUB; USPAT | OR | ON | 2005/01/27 08:50 |
| S10 | 539 | S7 same (wafer semiconductor chip die dice) same ((active adj surface) pad underbump (under adj bump)) | US-PGPUB; USPAT | OR | ON | 2005/01/27 08:43 |
| S11 | 453 | S7 same ((wafer semiconductor chip die dice) with ((active adj surface) pad underbump (under adj bump))) | US-PGPUB; USPAT | OR | ON | 2005/01/27 08:44 |
| S12 | 5686 | 438/108.ccls. 438/612.ccls. 438/613.ccls. 438/614.ccls. 257/738.ccls. 257/e21.508.ccls. 29/842.ccls. | US-PGPUB; USPAT | OR | ON | 2005/01/27 08:47 |

| S13 | 594 | S12 and S7 | US-PGPUB; USPAT | OR | ON | 2005/01/27 08:47 |
|-----|-----|-----------|-----------------|-----|-----|-------------------|
| S14 | 517 | S13 and ((wafer semiconductor chip die dice) same ((active adj surface) pad underbump (under adj bump))) | US-PGPUB; USPAT | OR | ON | 2005/01/27 08:49 |
| S15 | 228 | S12 and S10 | US-PGPUB; USPAT | OR | ON | 2005/01/27 11:37 |
| S16 | 812 | S7 and ((wafer semiconductor chip die dice) same ((active adj surface) pad) same (underbump (under adj bump) passivat$6 reflow$6)) | US-PGPUB; USPAT | OR | ON | 2005/01/27 09:08 |
| S17 | 344 | S7 same (wafer semiconductor chip die dice) same ((active adj surface) pad) same (underbump (under adj bump) passivat$6 reflow$6) | US-PGPUB; USPAT | OR | ON | 2005/01/27 17:13 |